

Minimum annular ring on inner layer

Minimum annular ring on inner layer – this is a parameter used in manufacturing, i.e. a value demonstrating the technological capability of the PCB manufacturer.

This parameter is often mixed up with annular rings used in design. Namely – during design, all hole sizes are defined as final, i.e. together with plating, which means that the PCB manufacturer must increase the initial drilling sizes by 0.1 mm.

Consequently, the minimum annular ring decreases by 0.1 mm and does not fit in technological frames anymore!

This often leads to a situation where the designer uses the minimum parameter in the inner layer during the construction of a board and is disappointed when the manufacturer sends the gerber files back.

To avoid confusion, please take into account that holes may be increased by the manufacturer during construction or use the parameters provided in the subsection “Design rules”.

The permitted minimum annular ring in the inner layer is larger than the one in the outer layer. The reason for that is the fact that the shrinkage of the inner layer during pressing is more difficult to control.

